





N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
201/	$21m\Omega$ @ V_{GS} = $10V$	6.5A
20V	$25m\Omega$ @ V_{GS} = $4.5V$	5.2A

Description

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

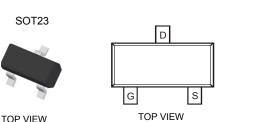
- General Purpose Interfacing Switch
- Power Management Functions

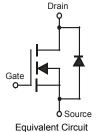
Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 ³
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (approximate)





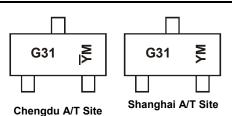
Ordering Information (Notes 4 & 5)

Part Number	Qualification	Case	Packaging
DMG3420U-7	Standard	SOT23	3000/Tape & Reel
DMG3420UQ-7	Automotive	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html
- 5. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.

Marking Information



G31 = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site) \overline{Y} M = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Y or \overline{Y} = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Date Code Kev

Date Code Ney												
Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Υ		Z	Α		В		С
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characte	eristic		Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage		V _{GSS}	±12	V	
Continuous Drain Current (Note 6)	T _A = +25°C T _A = +85°C	I _D	5.47 3.43	А	
Pulsed Drain Current (Note 7)			I _{DM}	20	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	0.74	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 6)	$R_{\theta JA}$	167	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

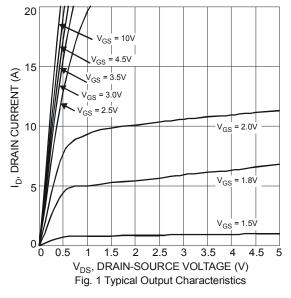
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

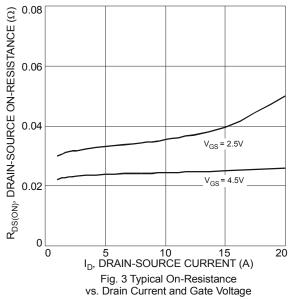
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	•		•	•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1.0	μΑ	V _{DS} = 20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	V _{GS} = ±12V, V _{DS} = 0V	
ON CHARACTERISTICS (Note 8)				•			
Gate Threshold Voltage	V _{GS(th)}	0.5	0.95	1.2	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
		_	21	29		V _{GS} = 10V, I _D = 6A	
Static Drain-Source On-Resistance			25	35	mΩ	$V_{GS} = 4.5V, I_D = 5A$	
Static Drain-Source On-Resistance	R _{DS(ON)}		34	48		$V_{GS} = 2.5V, I_D = 4A$	
			65	91		V _{GS} = 1.8V, I _D = 2A	
Forward Transfer Admittance	Y _{fs}		9	_	S	V _{DS} = 5V, I _D = 3.8A	
Diode Forward Voltage	V _{SD}	_	0.75	1.0	V	V _{GS} = 0V, I _S = 1A	
DYNAMIC CHARACTERISTICS (Note 9)				•			
Input Capacitance	C _{iss}	1	434.7	_	pF		
Output Capacitance	Coss		69.1	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	_	61.2	_	pF	1 - 1.0Wi12	
Gate Resistance	Rg	_	1.53	_	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz	
Total Gate Charge	Qg	_	5.4	_	nC		
Gate-Source Charge	Q _{gs}	_	0.9	_	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 6A$	
Gate-Drain Charge	Q_{gd}	_	1.5	_	nC	ID - OA	
Turn-On Delay Time	t _{D(on)}	_	6.5	_	ns		
Turn-On Rise Time	tr	_	8.3	_	ns	$V_{DD} = 10V, V_{GS} = 5V,$	
Turn-Off Delay Time	t _{D(off)}		21.6	_	ns	$R_L = 1.7\Omega$, $R_G = 6\Omega$	
Turn-Off Fall Time	t _f	_	5.3	_	ns	1	

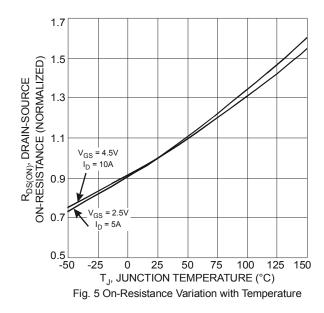
Notes:

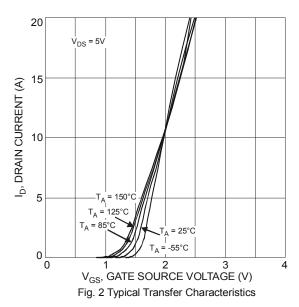
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 7. Repetitive rating, pulse width limited by junction temperature. 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to production testing.

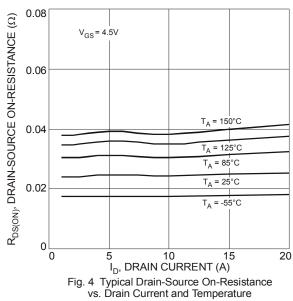












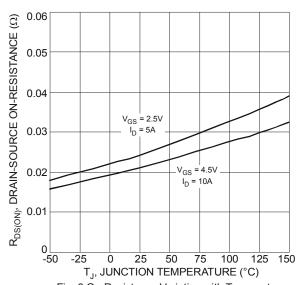


Fig. 6 On-Resistance Variation with Temperature



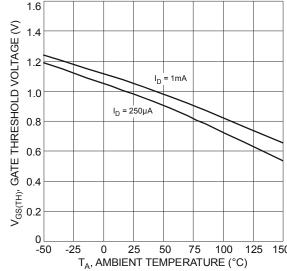
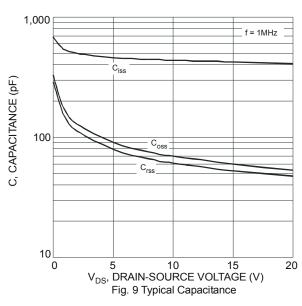
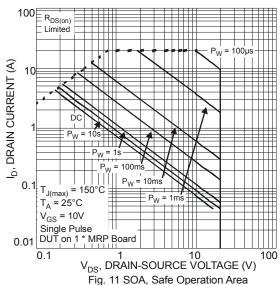
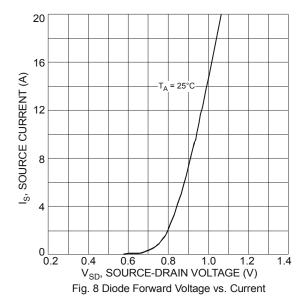
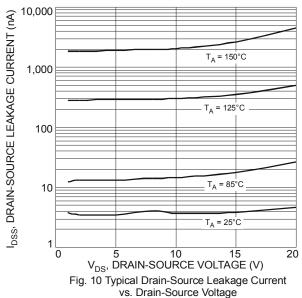


Fig. 7 Gate Threshold Variation vs. Ambient Temperature











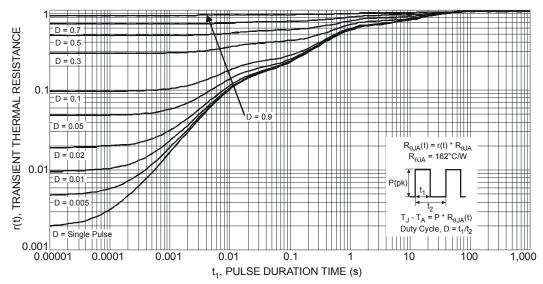
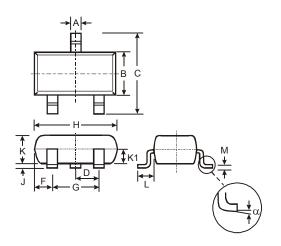


Fig. 12 Transient Thermal Response

Package Outline Dimensions

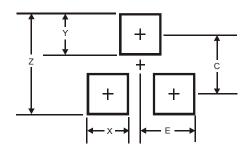
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
7	0.013	0.10	0.05				
K	0.903	1.10	1.00				
K1	-	-	0.400				
L	0.45	0.61	0.55				
М	0.085	0.18	0.11				
α	0°	8°	-				
All Dimensions in mm							

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.9
Х	8.0
Υ	0.9
С	2.0
E	1.35



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